	BLE STAN				ST	ORAGE							
	TEMPERATURE RANGE		-55 °C TO 85 °C ⁽¹⁾ T			TEMPERATURE RANGE			-10 °C	TO 60	°C (2)		
RATING	VOLTAGE		100 V AC STORAGE I RANGE				40 % TO 70 % ⁽²⁾						
	CURRENT		0.5 Å (signal contact) $^{(3)}$		-	OPERATING HUMIDITY RANGE			RELATIVE HUMIDITY 8			nax	
	SUNKLINI		3 A (MF CONTACT)				(NOT DEWED)						
			SPEC	IFICA	TION	S							
IT	EM		TEST METHOD				REQ	UIREN	MENTS		QT	A	
CONSTRI	JCTION												
	XAMINATION		Y AND BY MEASURING IN	ISTRUM	ENT.	ACCOF	RDING TO	DRAWI	NG.		×	>	
			MED VISUALLY.								×	>	
			D mA(DC OR 1000Hz)					NT	00 0 144	X	<u> </u>	1	
CONTACT RESISTANCE						SIGNAL CONTACT : 90 m Ω MAX. MF CONTACT : 30 m Ω MAX.					×	-	
	RESISTANCE	250 V DC. 300 V AC FOR 1 min.				1000 MΩ MIN. NO FLASHOVER OR BREAKDOWN.					×	-	
VOLTAGE PROOF MECHANICAL CHAR/						NO FLASHOVER OR BREAKDOWN.					×	-	
MECHANI					2			CE	30 N M	ΔΥ	×	 _	
	AND AL FORCES	MEASURED BY APPLICABLE CONNECTOR.				INSERTION FORCE: 30 N MAX. WITHDRAWAL FORCE: 3 N MIN.						-	
MECHANICA	4L	500 TIMES INSERTIONS AND EXTRACTIONS				1 CONTACT RESISTANCE:					×	1 -	
OPERATION	١						GNAL CONTACT : $100 \text{ m} \Omega \text{ MAX}$. F CONTACT : $40 \text{ m} \Omega \text{ MAX}$.						
						② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.							
VIBRATION		FREQUENCY 10 TO 55 TO 10Hz, APPROX 5min				1 NO ELECTRICAL DISCONTINUITY OF					×	-	
		SINGLE AMPLITUDE : 0.75 mm, 10 CYCLES				1 μs.							
011001/		FOR 3 DIRECTIONS.							ACK AND LOOSENESS				
SHOCK		490 m/s ² , DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.				OF	PARTS.				×	-	
	MENTAL C			HONS.									
			DAT 40±2 °C, 90 ~ 9	95 %. 9	96 h.	① CO	NTACT RE	SISTAN	ICE:		×	- 1	
(STEADY ST	ΓΑΤΕ)					~			100 m Ω M	AX.			
RAPID CHAI		TEMPERATURE -55 → +85 °C				MF CONTACT : $40 \text{ m} \Omega \text{ MAX}.$					×	-	
TEMPERATI	URE	TIME 30 \rightarrow 30 min. UNDER 5 CYCLES. (RELOCATION TIME TO CHAMBER:WITHIN 2~3 MIN)				2 INS	ULATION	RESIST					
						 NO 		CDACK	:1000 MΩ				
		(RELOCATION TIME TO CHAMBER.WITHIN 2~3 MIN)				③ NO DAMAGE, CRACK AND LOOSENESS OF PARTS.							
SULFUR DIOXIDE		EXPOSED AT 25±2°C, 75±5%RH, 25 PPM FOR				NO HEAVY CORROSION.					×	-	
		96 h.											
REGIGTANO	E TO		ANDARD: JIS C 60068)				FORMATIO				×	<u> </u>	
RESISTANCE TO SOLDERING HEAT		1)REFLOW SOLDERING : PEAK TMP : 260°CMAX REFLOW TMP: 220°CMIN FOR 60sec				-	SIVE LOC						
						TERMINAL.							
		,	ERING IRONS : 360°C MAX		sec.								
		SOLDERED AT SOLDER TEMPERATURE 240±3°C FOR IMMERSION DURATION, 3 sec.				A NEW UNIFORM COATING OF SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED.					×	-	
COUN	IT DE	SCRIPTI	ON OF REVISIONS		DESIG	INED		(CHECKED		DA	DATE	
∕0∖											1		
		PERATURE RISE CAUSED BY CURRENT-CARRYING. EANS A LONG-TERM STORAGE STATE SED PRODUCT BEFORE ASSEMBLY TO PCB. JRRENT APPLIES TO PER CONTACT. HEN ALL THE CONTACTS ARE USED FOR CURRENT CARRY fied. refer to JIS-C-5402.				APPR		D HS. OKAWA			15.0	6.3	
							CHECKE	D			15.0	6.3	
	(3) THE RATED CU						DESIGNE	D	TH. SANC)	15.06.3		
Unless oth					CARRYING			1	TH. SANC)	15.06.30		
Unless otherwise specified, refer to JIS-C-5402. Note QT:Qualification Test AT:Assurance Test X:Applicable Test D					RAWING NO. ELC-349361-0								
			FICATION SHEET			NO.		FX18-40PS-0. 8H15					
RS												11	
		OSE ELECTRIC CO., LTD.			CODE NO.		UL5	CL579-0049-9-00				1/ [.]	
EODM UDOO11	<u> </u>						-					•	